PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT4746398

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
SATORU YAMAKI	12/13/2017
MAKOTO FUKUSHIMA	12/14/2017
KEISUKE NAMIKI	12/13/2017
OSAMU NABEYA	12/13/2017
SHINGO TOGASHI	12/13/2017
TOMOKO OWADA	12/14/2017

RECEIVING PARTY DATA

Name:	EBARA CORPORATION
Street Address:	11-1, HANEDA ASAHI-CHO, OHTA-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	144-8510

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	29630484

CORRESPONDENCE DATA

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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ATTORNEY DOCKET NUMBER:	EBARA-58560
NAME OF SUBMITTER:	BRYAN M. GALLO
SIGNATURE:	/bryanmgallo/
DATE SIGNED:	12/21/2017
	This document serves as an Oath/Declaration (37 CFR 1.63).

Total Attachments: 6

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Application No.:

Docket No.:

COMBINED DECLARATION AND ASSIGNMENT

ASSIGNMENT

Assignor(s)

NAME	Satoru YAMAKI
Address	c/o EBARA CORPORATION, 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo 1448510
NAME	Makoto FUKUSHIMA
Address	c/o EBARA CORPORATION, 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo 1448510
NAME	Keisuke NAMIKI
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NAME	Osamu NABEYA
Address	c/o EBARA CORPORATION, 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo 1448510
NAME	Shingo TOGASHI
Address	c/o EBARA CORPORATION, 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo 1448510
NAME	Tomoko OWADA
Address	c/o EBARA CORPORATION, 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo 1448510

Application No.:

Docket No.:

COMBINED DECLARATION AND ASSIGNMENT

WHEREAS, ASSIGNOR(S) (listed above), are inventor(s) of one or more inventions disclosed, described and/or claimed in the application referred to as Docket Number ("the invention"), which is entitled

ELASTIC MEMBRANE FOR SEMICONDUCTOR WAFER POLISHING

("the subject application"), and which claims priorities to patent application numbers JP2017-013970 filed on 06/29/2017 and JP2017-013971 filed on 06/29/2017 ("the priority applications"). I authorize and direct any of the attorneys responsible for prosecuting the subject application on behalf of the ASSIGNEE to insert the application number and filing date of the subject application in the final paragraph of this assignment.

AND WHEREAS, **EBARA CORPORATION**, ASSIGNEE, having a place of business at **11-1, HANEDA ASAHI-CHO, OHTA-KU, TOKYO 1448510 JAPAN**, is desirous of obtaining my entire right, title, and interest in, to, and under the invention:

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, ASSIGNOR(S), hereby sell, assign, transfer, and set over, unto the ASSIGNEE, its successors, legal representatives, and assigns, the entire right, title, and interest in, to, and under the invention, and all applications for industrial property protection, including without limitation, all applications for patents, utility models, inventors' certificates, and designs that have been filed, and that may hereafter be filed, in any country, that disclose, describe, and/or claim the invention, including, without limitation, the subject application and the priority application, and all extensions, renewals, and reissues of such applications, including all divisions and continuations in whole or in part; all patents granted on such applications in any country, and all extensions, renewals, and reissues of such patents, including all divisions and continuations in whole or in part; the right to file such applications in any country; and the right to claim for such applications in any country the priority rights derived from the priority application and the subject application under the International Convention for the Protection of Industrial Property, the Patent Laws of the United States, any other international agreement or protection, or the domestic laws of any country in which any such application is filed, as may be applicable.

AND ASSIGNOR(S) HEREBY covenant and agree that ASSIGNOR(S) have full right to convey the entire interest herein assigned, and that ASSIGNOR(S) have not executed, and will not execute, any agreement in conflict herewith.

Application No.:

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COMBINED DECLARATION AND ASSIGNMENT

AND ASSIGNOR(S) HEREBY further covenant and agree that ASSIGNOR(S) will communicate to the ASSIGNEE, its successors, legal representatives, and assigns, any facts known to ASSIGNOR(S) respecting the invention, and testify in any legal proceeding, sign all lawful papers, execute all disclaimers and all divisional, continuing, reissue, and foreign applications, make all rightful oaths, deliver upon request all papers, documents, affidavits, or other instruments that may be necessary or helpful in the prosecution of any application for industrial property protection describing and/or claiming the invention, and generally do everything possible to aid the ASSIGNEE, its successors, legal representatives, and assigns, to obtain and enforce proper protection for the invention in all countries.

Application No.:

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COMBINED DECLARATION AND ASSIGNMENT

DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76)

Title of Invention	ELASTIC MEMBRANE FOR SEMICONDUCTOR WAFER POLISHING

As the below named inventor(s), I/we declare that:

This combined declaration and assignment is directed to:

☒ the attached application, or

☐ United States application or PCT international application number filed on .

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

Notice to Inventor(s): A person may not execute this declaration unless that person has reviewed and understands the contents of the above-identified application, including the claims.

Notice to Inventor(s): A person may not execute this declaration unless that person is aware of the duty to disclose to the US Patent and Trademark Office all information known to the person to be material to patentability as defined in 37 CFR 1.56.

Satoru YAMAKI
Printed Name in English

Satoru Yamaki
Inventor's Signature

Dec. 13, 2017
Date

Application No.:

Docket No.:

COMBINED DECLARATION AND ASSIGNMENT

Makoto FUKUSHIMA
Printed Name in English

Makoto Fukushima
Inventor's Signature

Dec. 14, 2017
Date

Keisuke NAMIKI
Printed Name in English

Keisuke Namiki
Inventor's Signature

Dec. 13, 2017
Date

Osamu NABEYA
Printed Name in English

Osamu Nabeya
Inventor's Signature

Dec. 13. 2017
Date

Shingo TOGASHI
Printed Name in English

Shingo Togashi
Inventor's Signature

Dec. 13. 2017
Date

Application No.:

Docket No.:

COMBINED DECLARATION AND ASSIGNMENT

Tomoko OWADA
Printed Name in English

Tomoko Owada
Inventor's Signature

Dec. 14. 2017
Date

The foregoing Combined Declaration and Assignment covers patent application number __________, filed on ________________.

Name of Attorney:
Registration No.:
Date of Insertion: